

Description

The UL3324P5A is an ultra low capacitance TVS array, utilizing leading monolithic silicon technology to provide fast response time and low ESD clamping voltage, making this device an ideal solution for protecting voltage sensitive high-speed data lines.

The UL3324P5A has an ultra-low capacitance with a typical value at 0.3pF, and complies with the IEC 61000-4-2 (ESD) standard with $\pm 15\text{kV}$ air and $\pm 8\text{kV}$ contact discharge. The flow through style package allows for easy PCB layout and matched trace lengths necessary to maintain consistent impedance between high speed differential lines such as USB 3.0 and HDMI.

The small size, ultra-low capacitance and high ESD surge protection make UL3324P5A an ideal choice to protect HDMI, MDDI, USB 3.0 and other high speed ports.

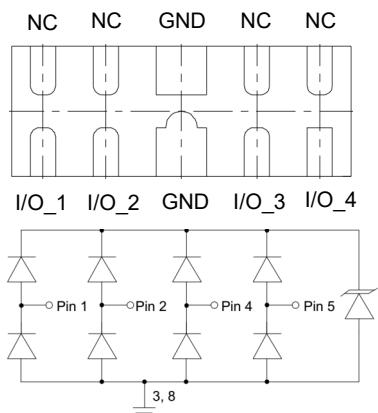
Features

- ◆ Ultra low capacitance: 0.3pF typical (I/O to I/O)
- ◆ Ultra low leakage: nA level
- ◆ Low operating voltage: 3.3 V
- ◆ Low clamping voltage
- ◆ Up to 4 lines protects
- ◆ Complies with following standards:
 - IEC 61000-4-2 (ESD) immunity test
 - Air discharge: $\pm 15\text{kV}$
 - Contact discharge: $\pm 8\text{kV}$
 - IEC61000-4-5 (Lightning) : 4A(8/20 μs)
- ◆ ROHS Compliant

Mechanical Characteristics

- ◆ Package: DFN2510-10 (2.5 x1.0 x0.5mm)
- ◆ Lead Finish: Matte Tin
- ◆ Case Material: "Green" Molding Compound
- ◆ Moisture Sensitivity: Level 3 per J-STD-020
- ◆ Terminal Connections: See Diagram Below
- ◆ Marking Information: See Below

Dimensions and Pin Configuration



Circuit and Pin Schematic

Applications

- ◆ HDMI 1.3 & 1.4, USB 2.0 & 3.0 and MDDI ports
- ◆ Monitors and flat panel displays
- ◆ Set-top box and digital TV
- ◆ Video graphics cards
- ◆ Digital video interface(DVI)
- ◆ Notebook Computers
- ◆ PCI express and Serial SATA ports

Marking Information



117 = Device Marking Code

XY = Wafer code

Dot denotes Pin1

Ordering Information

Part Number	Marking	Packaging	Reel Size
UL3324P5A	117XY	3000/Tape & Reel	7 inch

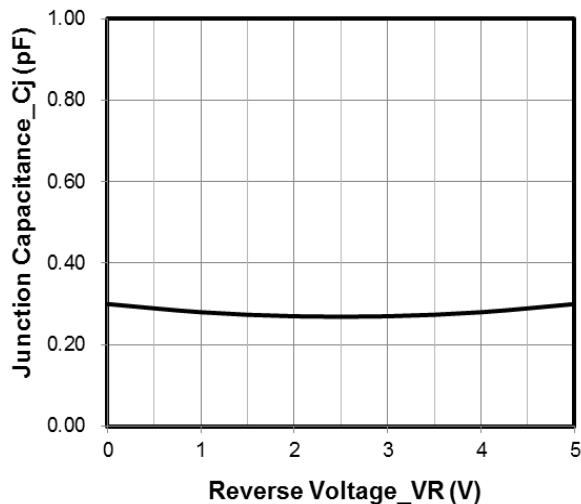
Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Value	Unit
Peak Pulse Power ($tp=8/20\mu\text{s}$)	P_{PP}	40	W
Peak Pulse Current ($tp=8/20\mu\text{s}$)	I_{PP}	4	A
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	V_{ESD}	± 15 ± 8	kV
Operating Temperature Range	T_J	-55 to +125	$^\circ\text{C}$
Storage Temperature Range	T_{stg}	-55 to +125	$^\circ\text{C}$

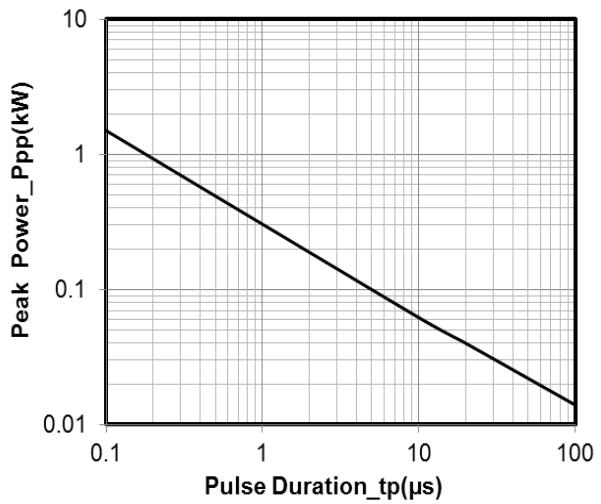
Electrical Characteristics ($T_A=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Working Voltage	V_{RWM}			3.3	V	Any I/O pin to ground
Breakdown Voltage	V_{BR}	5.8			V	$I_T = 2\mu\text{A}$, any I/O pin to ground
Breakdown Voltage	V_{BR}		8		V	$I_T = 1\text{mA}$, any I/O pin to ground
Reverse Leakage Current	I_R			0.5	μA	$V_{RWM} = 3.3\text{V}$, any I/O pin to ground
Clamping Voltage	V_C			9	V	$I_{PP} = 1\text{A}$ ($8 \times 20\mu\text{s}$ pulse), any I/O pin to ground
Clamping Voltage	V_C			10	V	$I_{PP} = 4\text{A}$ ($8 \times 20\mu\text{s}$ pulse), any I/O pin to ground
Junction Capacitance	C_J		0.3	0.4	pF	$VR = 0\text{V}$, $f = 1\text{MHz}$, between I/O pins
Junction Capacitance	C_J		0.6	0.8	pF	$VR = 0\text{V}$, $f = 1\text{MHz}$, any I/O pin to ground

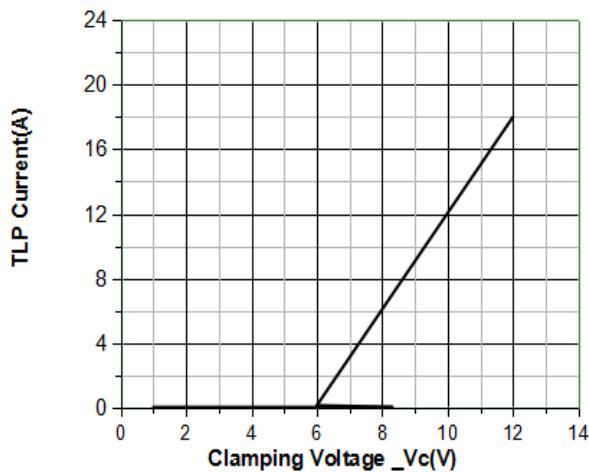
Typical Performance Characteristics ($T_A=25^\circ\text{C}$ unless otherwise Specified)



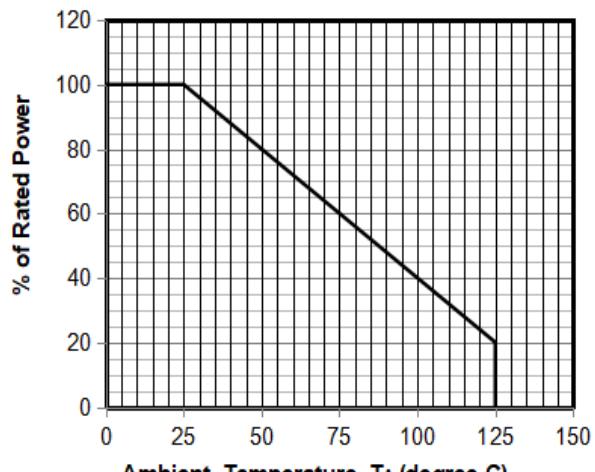
Junction Capacitance vs. Reverse Voltage



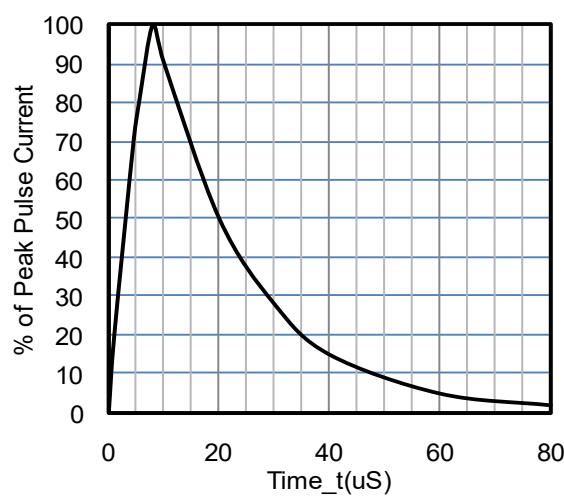
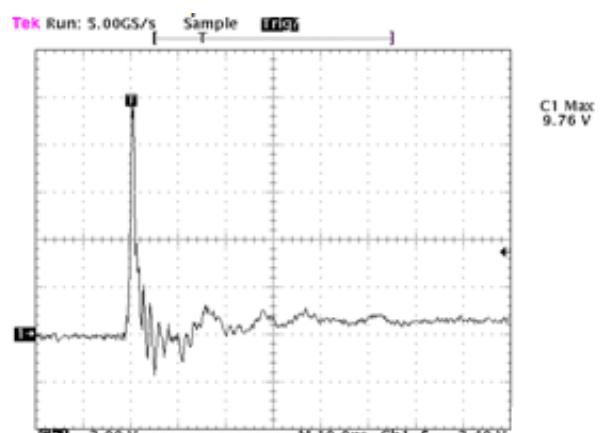
Peak Pulse Power vs. Pulse Time



TLP Characteristic (Positive Pulse)



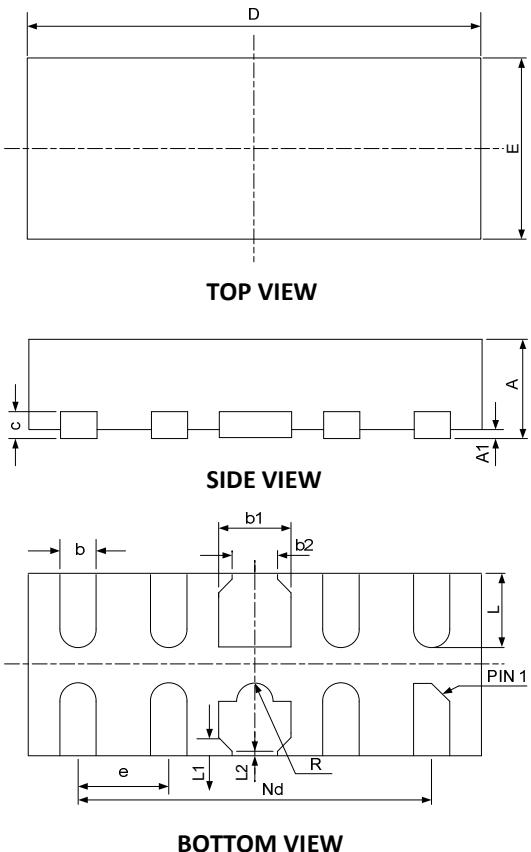
Power Derating Curve

8 X 20 μs Pulse Waveform

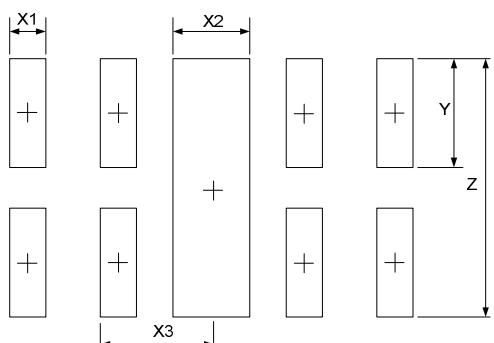
Note: Data is taken with a 10x attenuator

Contact discharge current waveform

per IEC61000-4-2

DFN2510-10 Package Outline Drawing

SYM	DIMENSIONS					
	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.45	0.50	0.55	0.018	0.020	0.022
A1	0.00	0.02	0.05	0.000	0.001	0.002
b	0.15	0.20	0.25	0.006	0.008	0.010
b1	0.35	0.40	0.45	0.014	0.016	0.018
b2	0.20	0.25	0.30	0.008	0.010	0.012
c	0.10	0.15	0.20	0.004	0.006	0.008
D	2.45	2.50	2.55	0.098	0.100	0.102
e	0.50BSC			0.020BSC		
Nd	2.00BSC			0.080BSC		
E	0.95	1.00	1.05	0.038	0.040	0.042
L	0.35	0.40	0.45	0.014	0.016	0.018
L1	0.075REF			0.003REF		
L2	0.050REF			0.002REF		
h	0.08	0.12	0.15	0.003	0.005	0.006
R	0.05	0.10	0.15	0.002	0.004	0.006

Suggested Land Pattern

SYM	DIMENSIONS	
	MILLIMETERS	INCHES
X1	0.200	0.008
X2	0.400	0.016
X3	0.500	0.020
Y	0.600	0.024
Z	1.400	0.056